

TEXT SEARCH

| L Number | Hits | Search Text | DB | Time stamp |
|----------|---------|--|---|------------------|
| - | 1563 | (solder near3 length) or (solder near3 segment\$1) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/13 11:29 |
| - | 2345054 | connector or connecting or interposer or interconnect or interconnecting | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/13 11:25 |
| - | 822 | ((solder near3 length) or (solder near3 segment\$1)) and (connector or connecting or interposer or interconnect or interconnecting) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/13 11:12 |
| - | 642 | ((solder near3 length) or (solder near3 segment\$1)) and (connector or connecting or interposer or interconnect or interconnecting) and (substrate or board) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/13 11:23 |
| - | 180 | ((solder near3 length) or (solder near3 segment\$1)) and (connector or connecting or interposer or interconnect or interconnecting) not (((solder near3 length) or (solder near3 segment\$1)) and (connector or connecting or interposer or interconnect or interconnecting)) and (substrate or board) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/13 11:27 |
| - | 20 | solder with bearing with wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/13 11:54 |
| - | 1 | solder adj bearing adj wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/13 11:32 |
| - | 5500 | solder and substrate and groove | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/13 11:33 |
| - | 3697 | (connector or connecting or interposer or interconnect or interconnecting) and (solder and substrate and groove) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/13 11:33 |
| - | 56 | ((connector or connecting or interposer or interconnect or interconnecting) and (solder and substrate and groove)) and ((solder near3 length) or (solder near3 segment\$1)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/13 11:33 |
| - | 3 | solder near3 bearing near3 wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/13 11:55 |
| - | 16 | (solder adj bearing or solder-bearing) near3 substrate | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/14 12:07 |
| - | 1 | (wafer) near3 (groove) near3 (solder) | USPAT | 2004/08/17 16:25 |
| - | 14 | (wafer) with (groove) with (solder) | USPAT | 2004/08/17 16:26 |
| - | 10 | (wafer) with (channel\$1) with (solder) | USPAT | 2004/08/17 16:30 |
| - | 20 | (wafer) with (groove\$1) with (solder) | USPAT | 2004/08/17 16:26 |
| - | 30 | ((wafer) with (groove) with (solder)) or ((wafer) with (channel\$1) with (solder)) or ((wafer) with (groove\$1) with (solder)) | USPAT | 2004/08/17 16:26 |

| | | | | |
|---|-----|--|---|------------------|
| - | 24 | (interconnect or interposer) with (channel\$1 or groove\$1) with (solder) | USPAT | 2004/08/17 16:35 |
| - | 23 | ((interconnect or interposer) with (channel\$1 or groove\$1) with (solder)) not ((wafer) with (groove) with (solder)) or ((wafer) with (channel\$1) with (solder)) or ((wafer) with (groove\$1) with (solder))) | USPAT | 2004/08/17 16:31 |
| - | 104 | (interconnect or interposer or wafer) with (channel\$1 or groove\$1) with (solder) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/08/17 16:35 |
| - | 51 | ((interconnect or interposer or wafer) with (channel\$1 or groove\$1) with (solder)) not (((interconnect or interposer) with (channel\$1 or groove\$1) with (solder)) or ((wafer) with (groove\$1) with (solder)) or ((wafer) with (channel\$1) with (solder)) or ((wafer) with (groove) with (solder))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/17 16:36 |